



Material Content Data Sheet



Sales Product Name				BTS432E2 E3062A		Issued		26. September 2017	
MA#				MA000668708					
Package				PG-TO263-5-2		Weight*		1501.36 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	13.065	0.87	0.87	8702	8702	
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158		
	non noble metal	iron	7439-89-6	0.790	0.05		526		
	non noble metal	copper	7440-50-8	788.527	52.52	52.59	525210	525894	
	non noble metal	aluminium	7429-90-5	1.577	0.10	0.10	1050	1050	
wire	non noble metal	aluminium	7429-90-5	1.577	0.10	0.10	1050	1050	
encapsulation	organic material	carbon black	1333-86-4	6.246	0.42		4160		
	inorganic material	antimonytrioxide	1309-64-4	13.060	0.87		8699		
	plastics	brominated resin	-	14.763	0.98		9833		
	plastics	epoxy resin	-	107.884	7.19		71858		
	inorganic material	silicondioxide	60676-86-0	425.858	28.36	37.82	283650	378200	
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6887	6887	
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5		
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2279	2284	
glue	plastics	Polyimide	26023-21-2	0.410	0.03	0.03	273	273	
solder	non noble metal	tin	7440-31-5	0.142	0.01		94		
	noble metal	silver	7440-22-4	0.177	0.01		118		
	non noble metal	lead	7439-92-1	6.767	0.45	0.47	4507	4719	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		22		
	non noble metal	iron	7439-89-6	0.108	0.01		72		
	non noble metal	copper	7440-50-8	107.943	7.19	7.20	71897	71991	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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